

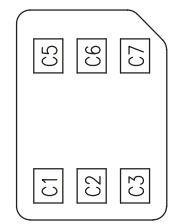
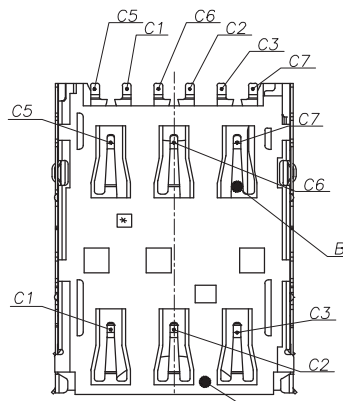
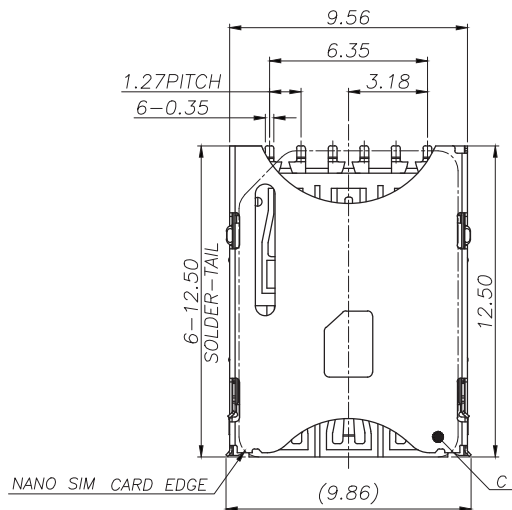
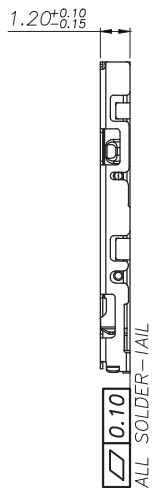
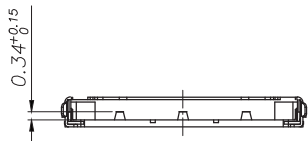
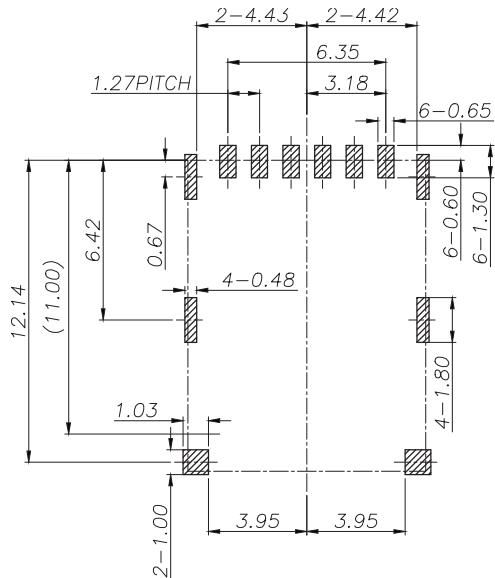
1

2

3

4

5



NANO SIM CARD PAD

TECHNICAL CHARACTERISTICS

MATERIAL
 INSULATOR: LCP
 FLAMABILITY RATING: UL94-V0
 COLOR: BLACK
 CONTACT MATERIAL: COPPER ALLOY
 CONTACT TYPE: STAMPED
 CONTACT PLATING: GOLD FLASH
 SHIELDING: STAINLESS STEEL NI PLATED
 QUALITY CLASS: 1500 MATING CYLCES

ENVIRONMENTAL
 OPERATING TEMPERATURE: -25°C UP TO +85°C
 COMPLIANCE: LEAD FREE AND ROHS

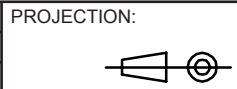
ELECTRICAL
 CURRENT RATING: 1.0A
 WORKING VOLTAGE: 15V DC
 INSULATION RESISTANCE: >500MΩ
 WITHSTANDING VOLTAGE: 500 VAC/min
 CONTACT RESISTANCE: 100mΩ max

SOLDERING
 JEDEC LEAD FREE REFLOW SOLDERING PROCESS

PACKAGING
 TAPE & REEL

Pin No.	Pin Assignment
C1	SUPPLY VOLTAGE (VCC)
C2	RESET(RST)
C3	CLOCK (CLK)
C5	GROUND(GND)
C6	PROGRAMMING VOLTAGE(VPP)
C7	I/O

RoHS Compliant			
G			
F			
E			
D			
C			
B			
A	13-JAN-15	PDF	QP
REV	DATE	FILE	BY



GENERAL TOLERANCE
 .X = +/- 0.2
 .XX = +/- 0.15

APPROVAL: NPr

UNIT: MM
 SCALE:
 SHEET: 1/3
 DRAW: QP

SIZE
A4

A

B

C

D